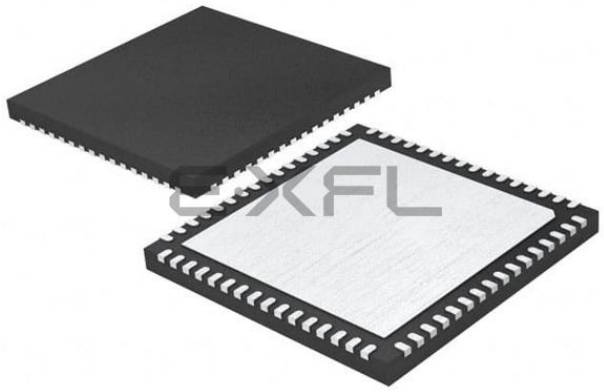
Microchip Technology - DSPIC33EP512MC506-E/MR Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc506-e-mr

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive resource. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

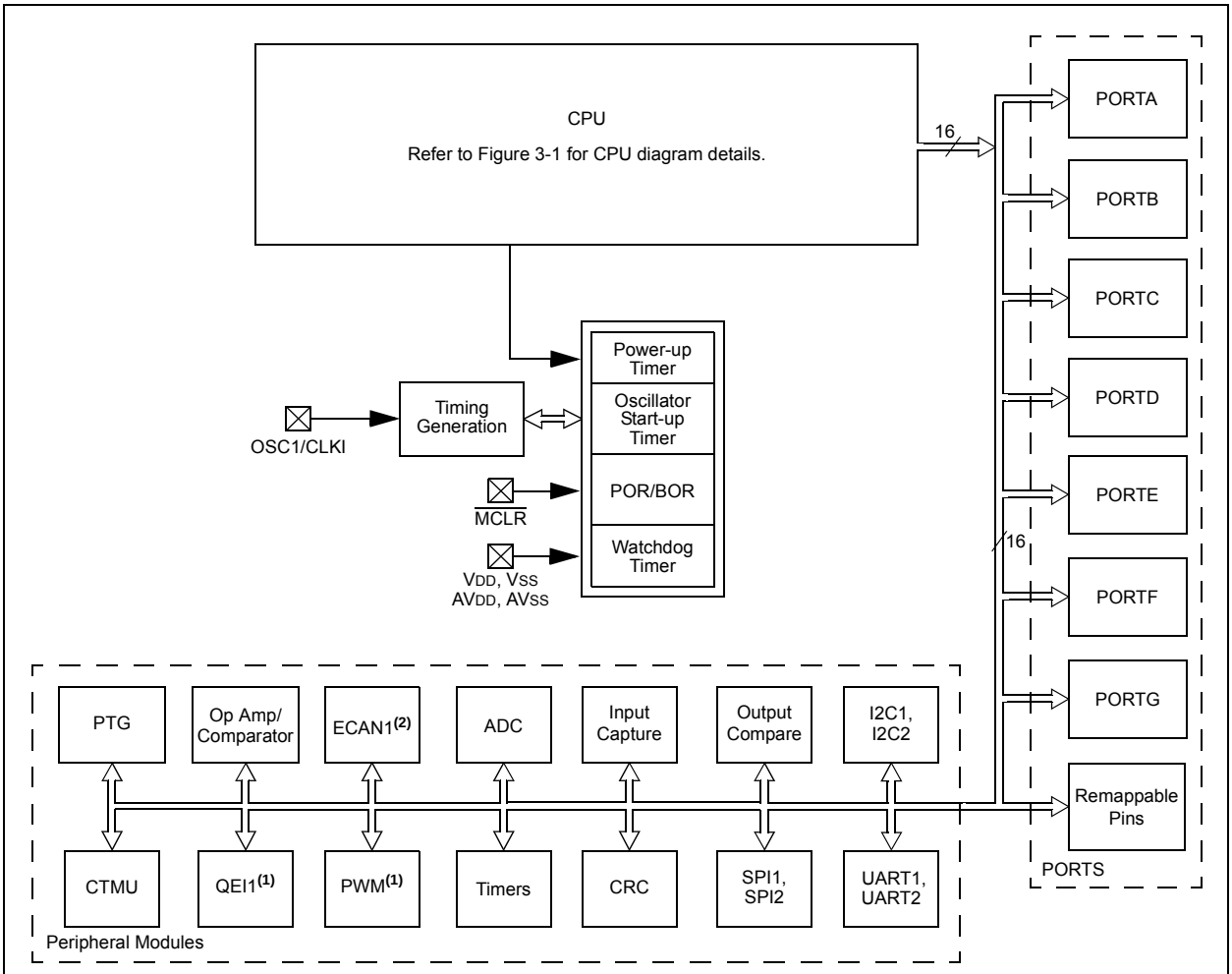
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X Digital Signal Controller (DSC) and Microcontroller (MCU) devices.

dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X BLOCK DIAGRAM



Note 1: This feature or peripheral is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This feature or peripheral is only available on dsPIC33EPXXXGP/MC50X devices.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

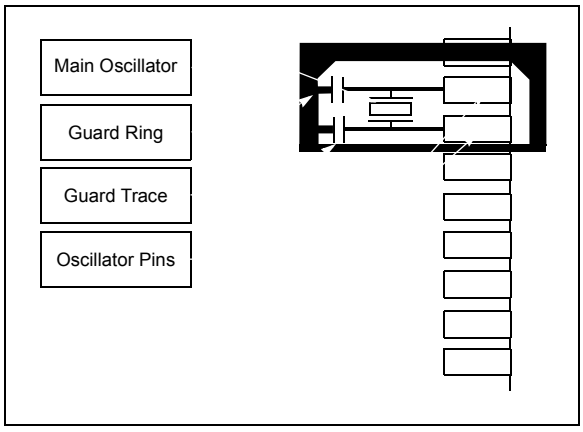


TABLE 4-46: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00	—	—	—	TRISA12	TRISA11	TRISA10	TRISA9	TRISA8	TRISA7	—	—	TRISA4	—	—	TRISA1	TRISA0	1F93
PORTA	0E02	—	—	—	RA12	RA11	RA10	RA9	RA8	RA7	—	—	RA4	—	—	RA1	RA0	0000
LATA	0E04	—	—	—	LATA12	LATA11	LATA10	LATA9	LATA8	LATA7	—	—	LATA4	—	—	LA1TA1	LA0TA0	0000
ODCA	0E06	—	—	—	ODCA12	ODCA11	ODCA10	ODCA9	ODCA8	ODCA7	—	—	ODCA4	—	—	ODCA1	ODCA0	0000
CNENA	0E08	—	—	—	CNIEA12	CNIEA11	CNIEA10	CNIEA9	CNIEA8	CNIEA7	—	—	CNIEA4	—	—	CNIEA1	CNIEA0	0000
CNPUA	0E0A	—	—	—	CNPUA12	CNPUA11	CNPUA10	CNPUA9	CNPUA8	CNPUA7	—	—	CNPUA4	—	—	CNPUA1	CNPUA0	0000
CNPDA	0E0C	—	—	—	CNPDA12	CNPDA11	CNPDA10	CNPDA9	CNPDA8	CNPDA7	—	—	CNPDA4	—	—	CNPDA1	CNPDA0	0000
ANSELA	0E0E	—	—	—	ANSA12	ANSA11	—	—	—	—	—	—	ANSA4	—	—	ANSA1	ANSA0	1813

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-47: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E	—	—	—	—	—	—	—	ANSB8	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	010F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-48: PORTC REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	0E20	TRISC15	—	TRISC13	TRISC12	TRISC11	TRISC10	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	BFFF
PORTC	0E22	RC15	—	RC13	RC12	RC11	RC10	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATC	0E24	LATC15	—	LATC13	LATC12	LATC11	LATC10	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	0E26	ODCC15	—	ODCC13	ODCC12	ODCC11	ODCC10	ODCC9	ODCC8	ODCC7	ODCC6	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	0000
CNENC	0E28	CNIEC15	—	CNIEC13	CNIEC12	CNIEC11	CNIEC10	CNIEC9	CNIEC8	CNIEC7	CNIEC6	CNIEC5	CNIEC4	CNIEC3	CNIEC2	CNIEC1	CNIEC0	0000
CNPUC	0E2A	CNPUC15	—	CNPUC13	CNPUC12	CNPUC11	CNPUC10	CNPUC9	CNPUC8	CNPUC7	CNPUC6	CNPUC5	CNPUC4	CNPUC3	CNPUC2	CNPUC1	CNPUC0	0000
CNPDC	0E2C	CNPDC15	—	CNPDC13	CNPDC12	CNPDC11	CNPDC10	CNPDC9	CNPDC8	CNPDC7	CNPDC6	CNPDC5	CNPDC4	CNPDC3	CNPDC2	CNPDC1	CNPDC0	0000
ANSELC	0E2E	—	—	—	—	ANSC11	—	—	—	—	—	—	—	—	ANSC2	ANSC1	ANSC0	0807

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES

Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
000 0000	I	Vss	010 1101	I	RPI45
000 0001	I	C1OUT(1)	010 1110	I	RPI46
000 0010	I	C2OUT(1)	010 1111	I	RPI47
000 0011	I	C3OUT(1)	011 0000	—	—
000 0100	I	C4OUT(1)	011 0001	—	—
000 0101	—	—	011 0010	—	—
000 0110	I	PTGO30(1)	011 0011	I	RPI51
000 0111	I	PTGO31(1)	011 0100	I	RPI52
000 1000	I	FINDX1(1,2)	011 0101	I	RPI53
000 1001	I	FHOME1(1,2)	011 0110	I/O	RP54
000 1010	—	—	011 0111	I/O	RP55
000 1011	—	—	011 1000	I/O	RP56
000 1100	—	—	011 1001	I/O	RP57
000 1101	—	—	011 1010	I	RPI58
000 1110	—	—	011 1011	—	—
000 1111	—	—	011 1100	—	—
001 0000	—	—	011 1101	—	—
001 0001	—	—	011 1110	—	—
001 0010	—	—	011 1111	—	—
001 0011	—	—	100 0000	—	—
001 0100	I/O	RP20	100 0001	—	—
001 0101	—	—	100 0010	—	—
001 0110	—	—	100 0011	—	—
001 0111	—	—	100 0100	—	—
001 1000	I	RPI24	100 0101	—	—
001 1001	I	RPI25	100 0110	—	—
001 1010	—	—	100 0111	—	—
001 1011	I	RPI27	100 1000	—	—
001 1100	I	RPI28	100 1001	—	—
001 1101	—	—	100 1010	—	—
001 1110	—	—	100 1011	—	—
001 1111	—	—	100 1100	—	—
010 0000	I	RPI32	100 1101	—	—
010 0001	I	RPI33	100 1110	—	—
010 0010	I	RPI34	100 1111	—	—
010 0011	I/O	RP35	101 0000	—	—
010 0100	I/O	RP36	101 0001	—	—
010 0101	I/O	RP37	101 0010	—	—
010 0110	I/O	RP38	101 0011	—	—
010 0111	I/O	RP39	101 0100	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See **Section 11.4.4.1 “Virtual Connections”** for more information on selecting this pin assignment.

2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

REGISTER 11-9: RPINR15: PERIPHERAL PIN SELECT INPUT REGISTER 15 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	HOME1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INDX1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **HOME1R<6:0>:** Assign QEI1 HOME1 (HOME1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **IND1XR<6:0>:** Assign QEI1 INDEX1 (INDX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

16.0 HIGH-SPEED PWM MODULE (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed PWM"** (DS70645) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices support a dedicated Pulse-Width Modulation (PWM) module with up to 6 outputs.

The high-speed PWMx module consists of the following major features:

- Three PWM generators
- Two PWM outputs per PWM generator
- Individual period and duty cycle for each PWM pair
- Duty cycle, dead time, phase shift and frequency resolution of TCY/2 (7.14 ns at FCY = 70MHz)
- Independent Fault and current-limit inputs for six PWM outputs
- Redundant output
- Center-Aligned PWM mode
- Output override control
- Chop mode (also known as Gated mode)
- Special Event Trigger
- Prescaler for input clock
- PWMxL and PWMxH output pin swapping
- Independent PWM frequency, duty cycle and phase-shift changes for each PWM generator
- Dead-time compensation
- Enhanced Leading-Edge Blanking (LEB) functionality
- Frequency resolution enhancement
- PWM capture functionality

Note: In Edge-Aligned PWM mode, the duty cycle, dead time, phase shift and frequency resolution are 8.32 ns.

The high-speed PWMx module contains up to three PWM generators. Each PWM generator provides two PWM outputs: PWMxH and PWMxL. The master time base generator provides a synchronous signal as a common time base to synchronize the various PWM outputs. The individual PWM outputs are available on the output pins of the device. The input Fault signals and current-limit signals, when enabled, can monitor and protect the system by placing the PWM outputs into a known "safe" state.

Each PWMx can generate a trigger to the ADC module to sample the analog signal at a specific instance during the PWM period. In addition, the high-speed PWMx module also generates a Special Event Trigger to the ADC module based on either of the two master time bases.

The high-speed PWMx module can synchronize itself with an external signal or can act as a synchronizing source to any external device. The SYNCI1 input pin that utilizes PPS, can synchronize the high-speed PWMx module with an external signal. The SYNCO1 pin is an output pin that provides a synchronous signal to an external device.

Figure 16-1 illustrates an architectural overview of the high-speed PWMx module and its interconnection with the CPU and other peripherals.

16.1 PWM Faults

The PWMx module incorporates multiple external Fault inputs to include FLT1 and FLT2 which are remappable using the PPS feature, FLT3 and FLT4 which are available only on the larger 44-pin and 64-pin packages, and FLT32 which has been implemented with Class B safety features, and is available on a fixed pin on all dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

These Faults provide a safe and reliable way to safely shut down the PWM outputs when the Fault input is asserted.

16.1.1 PWM FAULTS AT RESET

During any Reset event, the PWMx module maintains ownership of the Class B Fault, FLT32. At Reset, this Fault is enabled in Latched mode to ensure the fail-safe power-up of the application. The application software must clear the PWM Fault before enabling the high-speed motor control PWMx module. To clear the Fault condition, the FLT32 pin must first be pulled low externally or the internal pull-down resistor in the CNPDx register can be enabled.

Note: The Fault mode may be changed using the FLTMOD<1:0> bits (FCLCON<1:0>), regardless of the state of FLT32.

REGISTER 16-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER(1)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CLSRC4	CLSRC3	CLSRC2	CLSRC1	CLSRC0	CLPOL(2)	CLMOD
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0
FLTSRC4	FLTSRC3	FLTSRC2	FLTSRC1	FLTSRC0	FLTPOL(2)	FLTMOD1	FLTMOD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-10 **CLSRC<4:0>:** Current-Limit Control Signal Source Select for PWM Generator # bits
11111 = Fault 32
11110 = Reserved
•
•
•
01100 = Reserved
01011 = Comparator 4
01010 = Op Amp/Comparator 3
01001 = Op Amp/Comparator 2
01000 = Op Amp/Comparator 1
00111 = Reserved
00110 = Reserved
00101 = Reserved
00100 = Reserved
00011 = Fault 4
00010 = Fault 3
00001 = Fault 2
00000 = Fault 1 **(default)**

bit 9 **CLPOL:** Current-Limit Polarity for PWM Generator # bit(2)
1 = The selected current-limit source is active-low
0 = The selected current-limit source is active-high

bit 8 **CLMOD:** Current-Limit Mode Enable for PWM Generator # bit
1 = Current-Limit mode is enabled
0 = Current-Limit mode is disabled

Note 1: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

2: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

19.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Inter-Integrated Circuit™ (I^2C™)"** (DS70330) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

3: There are minimum bit rates of approximately FCY/512. As a result, high processor speeds may not support 100 Kbit/second operation. See timing specifications, IM10 and IM11, and the **"Baud Rate Generator"** in the "*dsPIC33/PIC24 Family Reference Manual*".

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices contains two Inter-Integrated Circuit (I^2C) modules: I2C1 and I2C2.

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The I^2C module has a 2-pin interface:

- The SCLx pin is clock
- The SDAx pin is data

The I^2C module offers the following key features:

- I^2C interface supporting both Master and Slave modes of operation
- I^2C Slave mode supports 7 and 10-bit addressing
- I^2C Master mode supports 7 and 10-bit addressing
- I^2C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation, detects bus collision and arbitrates accordingly
- Intelligent Platform Management Interface (IPMI) support
- System Management Bus (SMBus) support

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-2 **SID<10:0>:** Standard Identifier bits

bit 1 **SRR:** Substitute Remote Request bit
When IDE = 0:
1 = Message will request remote transmission
0 = Normal message
When IDE = 1:
The SRR bit must be set to '1'.

bit 0 **IDE:** Extended Identifier bit
1 = Message will transmit Extended Identifier
0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

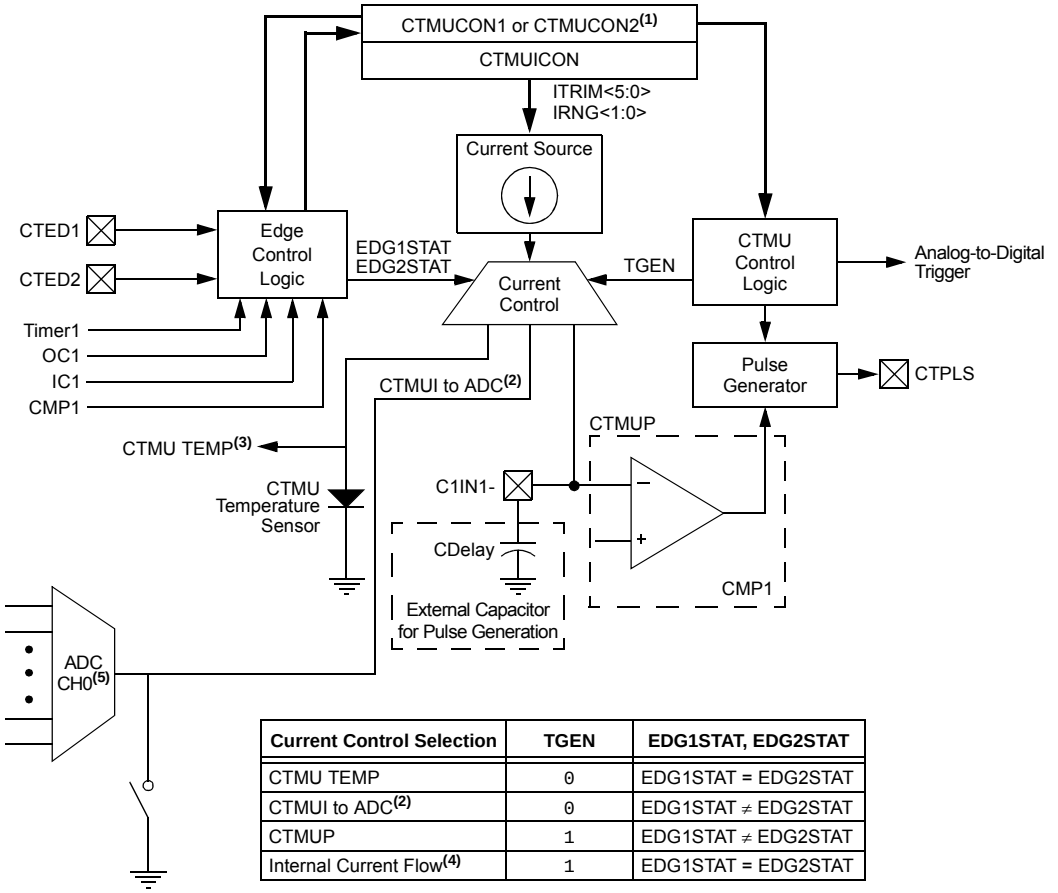
R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **EID<17:6>:** Extended Identifier bits

FIGURE 22-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	0	EDG1STAT = EDG2STAT
CTMUI to ADC(2)	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
Internal Current Flow(4)	1	EDG1STAT = EDG2STAT

Note 1: When the CTMU is not actively used, set TGEN = 1, and ensure that EDG1STAT = EDG2STAT. All other settings allow current to flow into the ADC or the C1IN1- pin. If using the ADC for other purposes besides the CTMU, set IDISSEN = 0. If IDISSEN is set to '1', it will short the output of the ADC CH0 MUX to VSS.

2: CTMUI connects to the output of the ADC CH0 MUX. When CTMU current is steered into this node, the current will flow out through the selected ADC channel determined by the CH0 MUX (see the CH0Sx bits in the AD1CHS0 register).

3: CTMU TEMP connects to one of the ADC CH0 inputs; see CH0SA and CH0SB (AD1CHS0<12:8,4:0).

4: If TGEN = 1 and EDG1STAT = EDG2STAT, CTMU current source is still enabled and may be shunted to VSS internally. This should be considered in low-power applications.

5: The switch connected to ADC CH0 is closed when IDISSEN (CTMUCON1<9>) = 1, and opened when IDISSEN = 0.

22.1 CTMU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

22.1.1 KEY RESOURCES

- **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NB1	CH123NB0	CH123SB
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NA1	CH123NA0	CH123SA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-9 **CH123NB<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample MUXB bits

In 12-bit mode (AD21B = 1), CH123NB is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
11	AN9	AN10	AN11
10(1,2)	OA3/AN6	AN7	AN8
0x	VREFL	VREFL	VREFL

bit 8 **CH123SB:** Channel 1, 2, 3 Positive Input Select for Sample MUXB bit

In 12-bit mode (AD21B = 1), CH123SB is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1(2)	OA1/AN3	OA2/AN0	OA3/AN6
0(1,2)	OA2/AN0	AN1	AN2

bit 7-3 **Unimplemented:** Read as '0'

bit 2-1 **CH123NA<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample MUXA bits

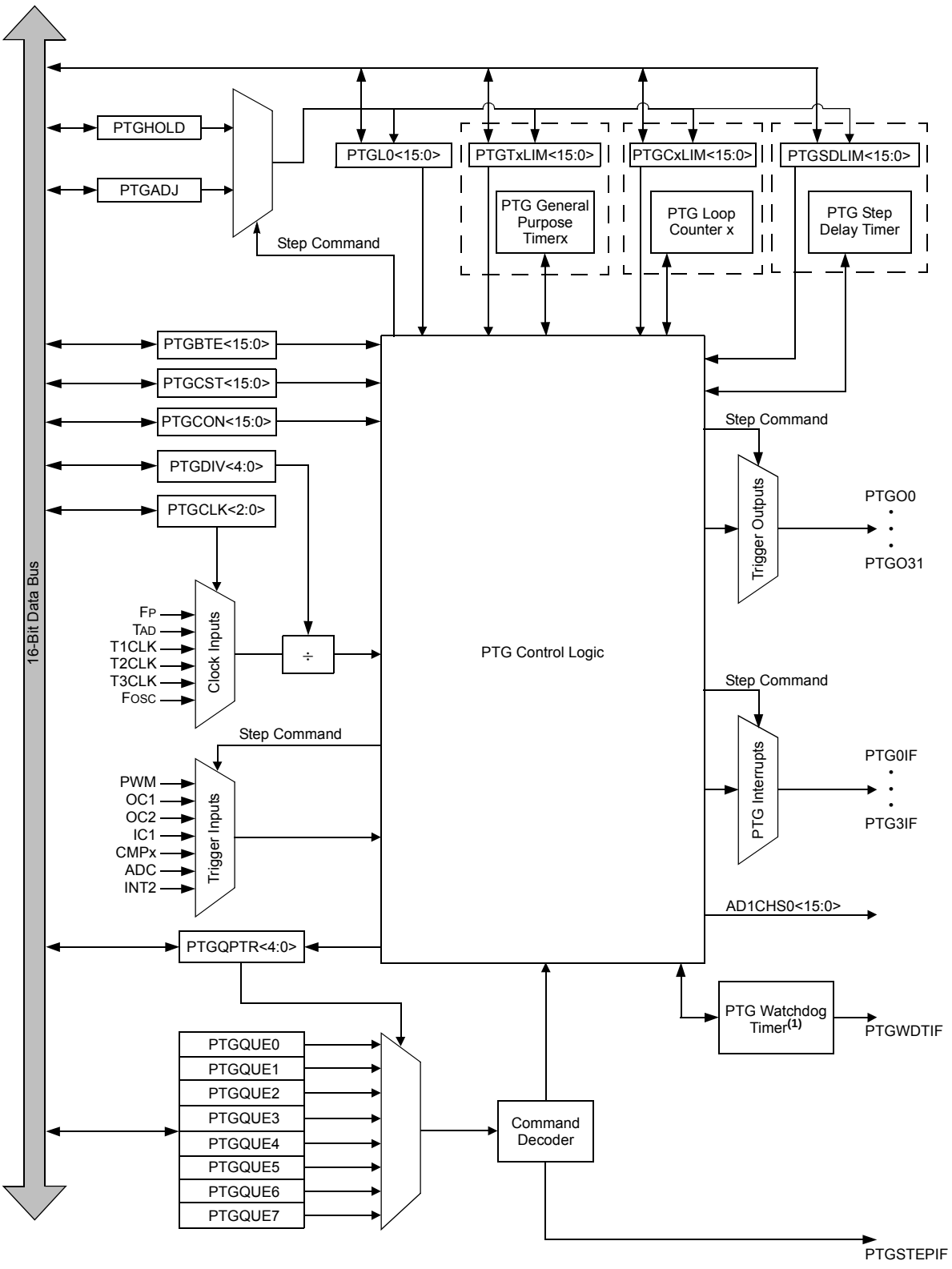
In 12-bit mode (AD21B = 1), CH123NA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
11	AN9	AN10	AN11
10(1,2)	OA3/AN6	AN7	AN8
0x	VREFL	VREFL	VREFL

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

FIGURE 24-1: PTG BLOCK DIAGRAM



Note 1: This is a dedicated Watchdog Timer for the PTG module and is independent of the device Watchdog Timer.

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS (CONTINUED)

Field	Description
Wm,Wn	Dividend, Divisor working register pair (direct addressing)
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions ∈ {W4 * W4,W5 * W5,W6 * W6,W7 * W7}
Wm*Wn	Multiplicand and Multiplier working register pair for DSP instructions ∈ {W4 * W5,W4 * W6,W4 * W7,W5 * W6,W5 * W7,W6 * W7}
Wn	One of 16 working registers ∈ {W0...W15}
Wnd	One of 16 destination working registers ∈ {W0...W15}
Wns	One of 16 source working registers ∈ {W0...W15}
WREG	W0 (working register used in file register instructions)
Ws	Source W register ∈ { Ws, [Ws], [Ws++], [Ws--], [++Ws], [--Ws] }
Wso	Source W register ∈ { Wns, [Wns], [Wns++], [Wns--], [++Wns], [--Wns], [Wns+Wb] }
Wx	X Data Space Prefetch Address register for DSP instructions ∈ {[W8] + = 6, [W8] + = 4, [W8] + = 2, [W8], [W8] - = 6, [W8] - = 4, [W8] - = 2, [W9] + = 6, [W9] + = 4, [W9] + = 2, [W9], [W9] - = 6, [W9] - = 4, [W9] - = 2, [W9 + W12], none}
Wxd	X Data Space Prefetch Destination register for DSP instructions ∈ {W4...W7}
Wy	Y Data Space Prefetch Address register for DSP instructions ∈ {[W10] + = 6, [W10] + = 4, [W10] + = 2, [W10], [W10] - = 6, [W10] - = 4, [W10] - = 2, [W11] + = 6, [W11] + = 4, [W11] + = 2, [W11], [W11] - = 6, [W11] - = 4, [W11] - = 2, [W11 + W12], none}
Wyd	Y Data Space Prefetch Destination register for DSP instructions ∈ {W4...W7}

29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16 and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		Any I/O Pin and $\overline{MCLR}$	VSS	—	0.2 VDD	V	
DI18		I/O Pins with SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	VSS	—	0.8	V	SMBus enabled
	VIH	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant	0.8 VDD	—	VDD	V	**(Note 3)**
		I/O Pins 5V Tolerant and $\overline{MCLR}$	0.8 VDD	—	5.5	V	**(Note 3)**
		I/O Pins with SDAx, SCLx	0.8 VDD	—	5.5	V	SMBus disabled
		I/O Pins with SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	ICNPU	**Change Notification Pull-up Current**					
DI30			150	250	550	μA	VDD = 3.3V, VPIN = VSS
	ICNPD	**Change Notification Pull-Down Current(4)**					
DI31			20	50	100	μA	VDD = 3.3V, VPIN = VDD

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current(1,2)**					
DI50		I/O Pins 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

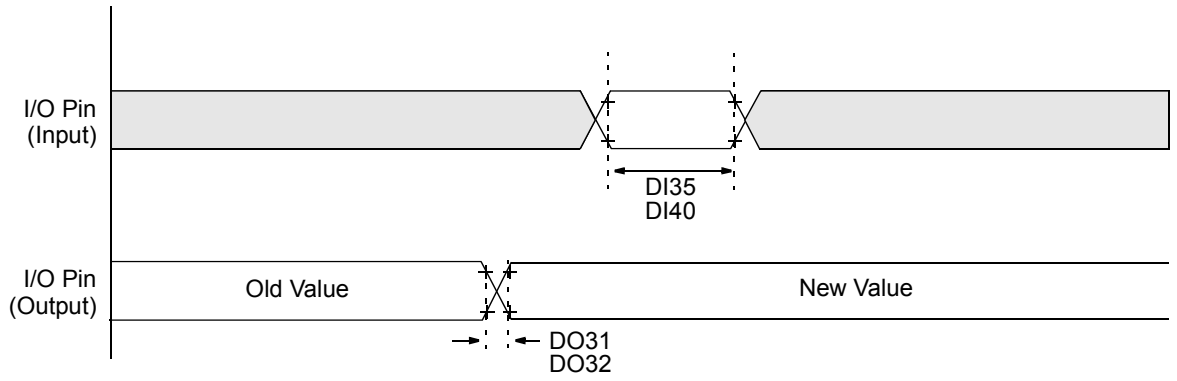
5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	10	ns	
DO32	TIOF	Port Output Fall Time	—	5	10	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

FIGURE 30-4: BOR AND MASTER CLEAR RESET TIMING CHARACTERISTICS

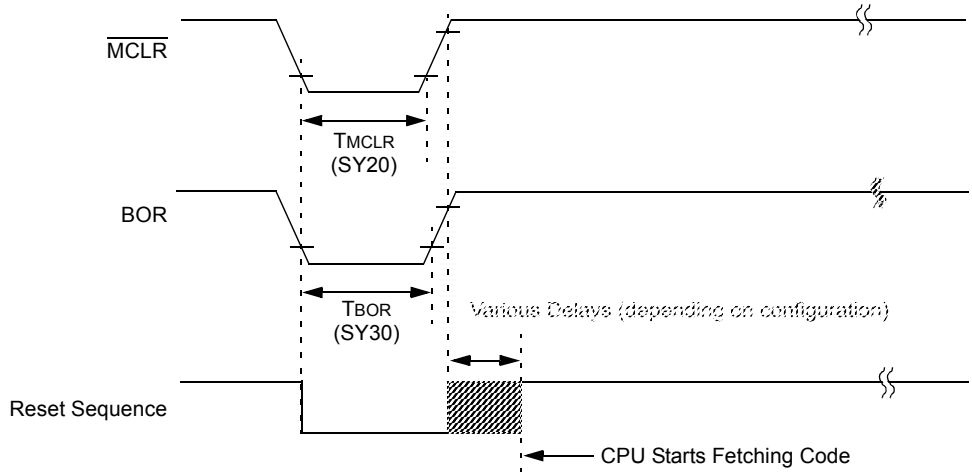
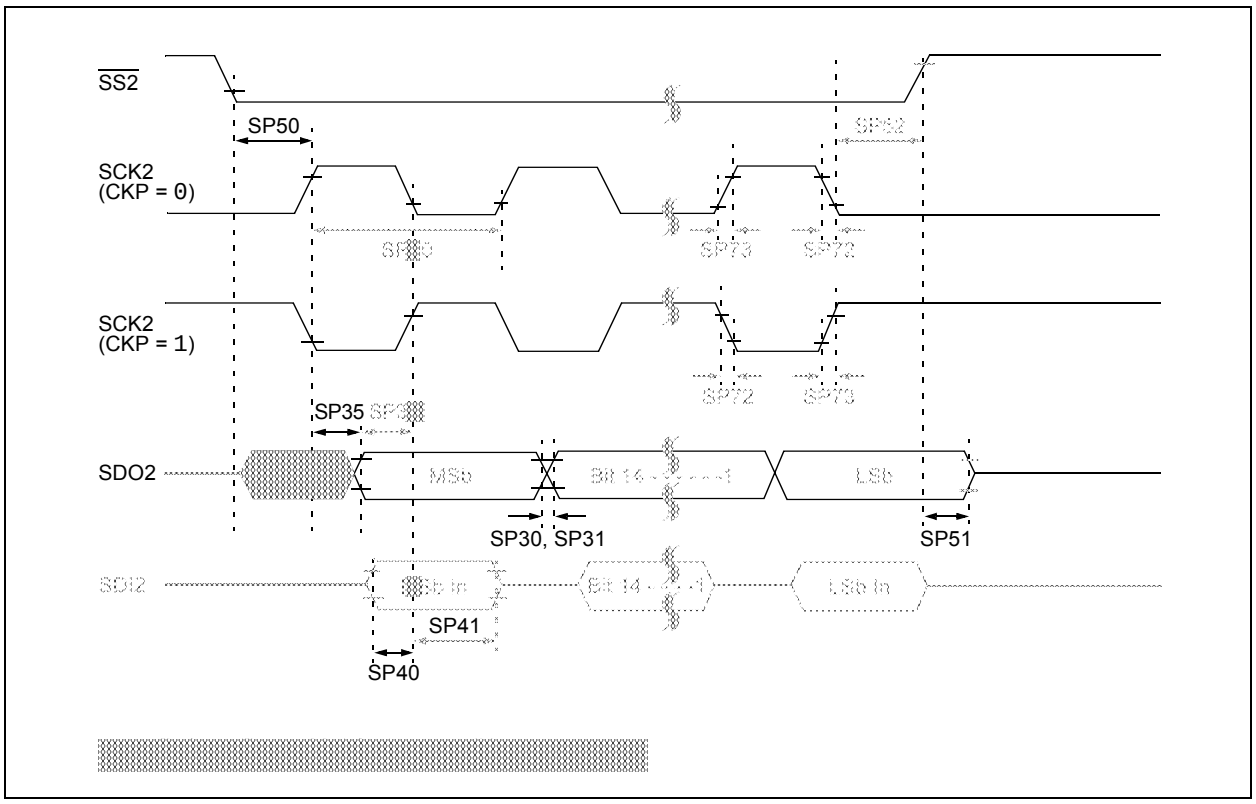
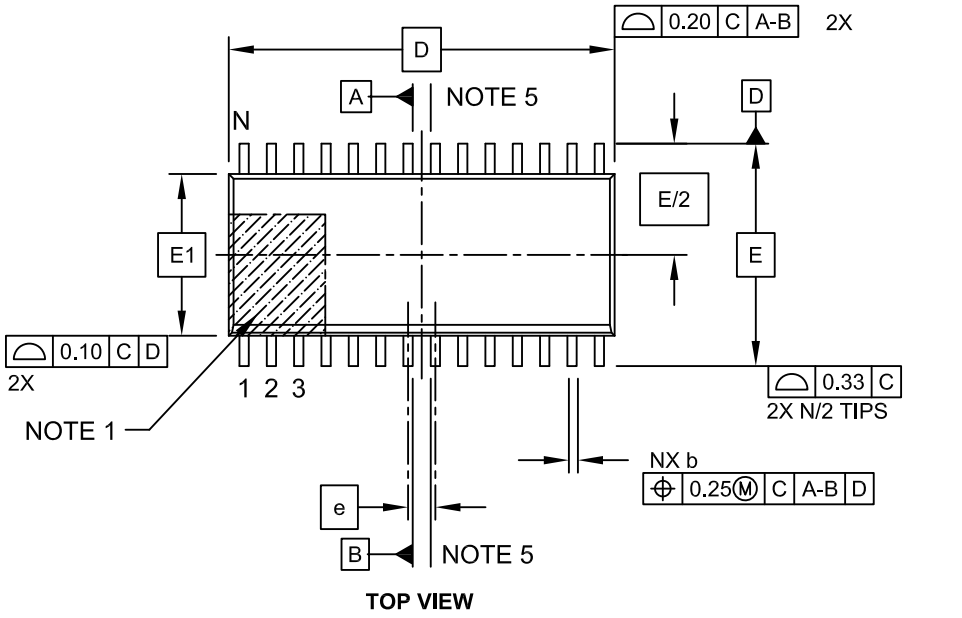


FIGURE 30-20: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

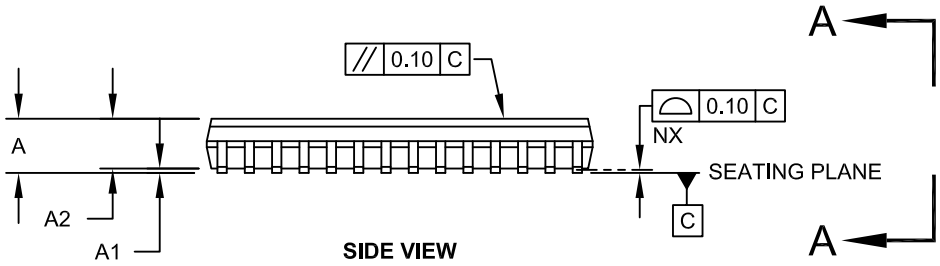


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

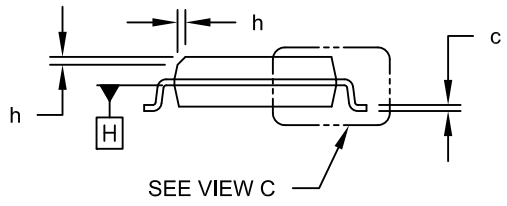
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2